6-103166-8 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 6-103166-8 PCB Mount Header, Right Angle, Wire-to-Board / Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board, Wire-to-Board

Number of Positions: 40

Number of Rows: 2

Features

E T E connectivity

Product Type Features

Connector Profile	Standard
Body Features	
Dielectric Withstanding Voltage (Max)	750 Vrms
Insulation Resistance	5000 MΩ
Electrical Characteristics	
Number of Rows	2
Number of Positions	40
PCB Mount Orientation	Right Angle
Connector Contact Load Condition	Fully Loaded
Configuration Features	
Connector & Contact Terminates To	Printed Circuit Board
Header Type	Fully Shrouded
Connector System	Board-to-Board, Wire-to-Board
PCB Connector Assembly Type	PCB Mount Header

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Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]
PCB Contact Termination Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
ermination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.43 mm[.135 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

Mechanical Attachment

Mating Retention	With
Mating Retention Type	Detent Window
Mating Alignment	With
Mating Alignment Type	Polarization
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Row-to-Row Spacing	2.54 mm[.1 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Housing Temperature Rating	Standard

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Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	
Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Agency/Standard	CSA
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	40
Packaging Type Product Compliance	Tray
Product Compliance For compliance documentation, visit the product page on TE.com>	
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Compliant
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Compliant Compliant
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU	Compliant
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC	Compliant Compliant
Product Compliance For compliance documentation, visit the product page on TE.com> EU RoHS Directive 2011/65/EU EU ELV Directive 2000/53/EC China RoHS 2 Directive MIIT Order No 32, 2016	Compliant Compliant No Restricted Materials Above Threshold Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235)

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

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Compatible Parts



Also in the Series AMPMODU Headers







Customers Also Bought



PCB Mount Header, Right Angle, Wire-to-Board / Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, AMPMODU Headers





Documents

Product Drawings 40 MODII HDR DRRA SHRD LF

English

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_6-103166-8_K.2d_dxf.zip

English

Customer View Model

ENG_CVM_6-103166-8_K.3d_igs.zip

English

Customer View Model

ENG_CVM_6-103166-8_K.3d_stp.zip

English

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Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Environmental Compliance

TE Material Declaration

English